Amendments to the Specification:

Please replace paragraph (0002) with the following rewritten paragraph:

In a system for producing semiconductors, a ceramic heater may be provided for heating a wafer so as to deposit a semiconductor thin film on the wafer from gaseous raw materials such as silane gas by means of thermal CVD or the like. So a called two-zone heater is known as such ceramic heater. Such two-zone heater hasheaters have a ceramic substrate and inner and outer resistance heat generators of a metal having a high melting point embedded within the substrate. Separate power supply terminals are connected to the respective heat generators so that electric power may be applied independently on the respective generators. The inner and outer heat generators may be thus independently controlled.

Please replace paragraph (0003) with the following rewritten paragraph:

Further, in JP-A 5-326112, a resistance heat generator of a ceramic heater is constituted by plural circuit patterns, each made of a high melting point metal. The circuit patterns are so arranged that they may supplement one another's defect portions. For example, one of the patterns has a defect portion such as a folded portion or a returning portion. In this case, another circuit pattern is overlapped on or over the defect portion of the one pattern.

Please replace paragraph (0006) with the following rewritten paragraph:

However, a production cost for a ceramic heater is high. In particular, a ceramic heater is supported with a tubular supporting member, which is then fixed onto a chamber. It is needed a thicker substrate is needed for the heater for providing a strength required for supporting the heater, so that a production cost for the ceramic heater is increased.

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In a preferred embodiment, the heating means is a heat resistor embedded in a ceramic substrate. Fig. 1 is a cross sectional view schematically showing a heating system 1 according to this embodiment. A metal and plate-shaped supporting member 4 has a flat-plate shaped portion 4b, and a flange portion 4a protruding from the peripheral part of the flat-plate shaped portion 4b. A ceramic substrate 2 is mounted on the surface 4c of the flat-plate shaped portion 4b. A heat resistor 3 is embedded in the ceramic substrate 2. A back face 2b of the ceramic substrate 2 is contacted with the surface 4c of the flat-plate shaped portion 4b to mount an object W on the mounting face 2b2a of the ceramic substrate 2. In the present example, the tip end of the flange portion 4a is protruded over the mounting face 2a to form a guide 5 for guiding the periphery of the object W.

Please replace paragraph (0023) with the following rewritten paragraph:

In a heating system 1C shown in Fig. 4, a heating means 1615 is mounted on the flat-plate shaped portion 4b of the plate shaped member 4. The heating means 1615 has flat plates 15a, 15b each made of an insulating material, and a heat generator 15c wound on the flat plate 15b. A ceramic substrate 16 is mounted on the heating means 15. The ceramic substrate 16 has a flat-plate shaped portion 16c and flange portion 16b. A guide 5 is formed inside of the flange portion 16b. 16d represents a back face and 16e represents a side face. The object W is mounted on the mounting face 16a of the ceramic substrate 16.

Please replace paragraph (0024) with the following rewritten paragraph:

In a heating system 1D shown in Fig. 5, a heating means 16A15 is mounted on the flat-plate shaped portion 4b of the plate shaped supporting member 4. The heating means 16A15 has flat plates 15a, 15b each made of an insulating material, and a heat generator 15c wounded on the flat plate 15b. A ceramic substrate 16A is mounted on the heating means 15. The object W is mounted on the mounting face 16a of the

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ceramic substrate 16A. A guide 5 is formed inside of the flange portion 4a of the plate shaped supporting member 4.